

# OL-NX5P3001

wafer level chip-scale package; 12 bumps; 1.36 x 1.66 x 0.51 mm, 0.4 mm pitch (Backside coating included)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP12
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-5-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.63	-	1.66	1.69	mm
E	package width	1.33	-	1.36	1.39	mm
A	seated height	0.47	-	0.51	0.55	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	12	-	



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2. Package outline

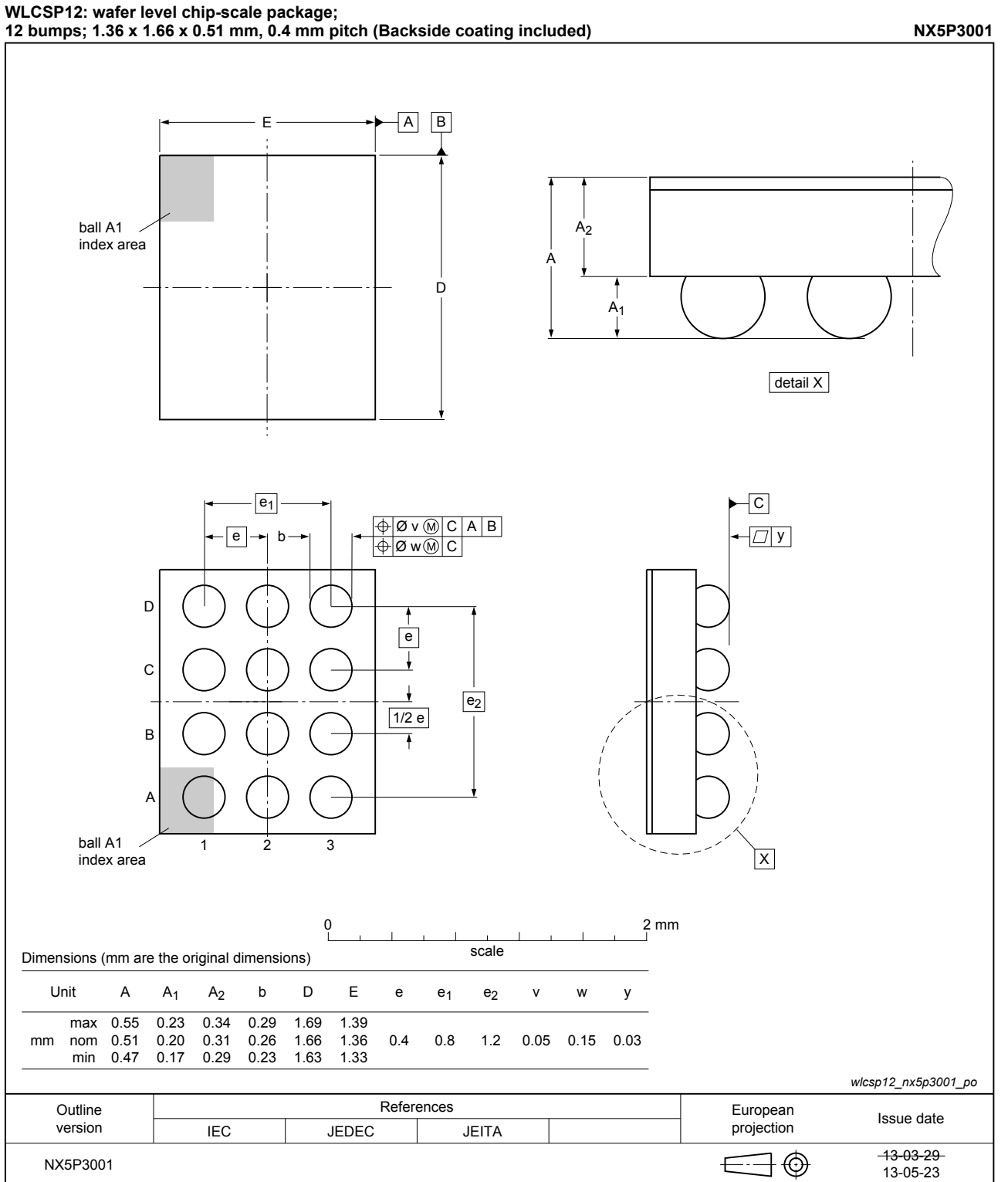


Fig. 1. Package outline WLCSP12 (OL-NX5P3001)

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### 3. Legal information

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